

UM1B~UM10B

Rev.D May.-2017



DATA SHEET

0.8A

UMB

0.8A Surface Mount Glass Passivated Bridge Rectifier,UMB thin package.

100V~1000V

0.8A

Glass Passivated Chip Junction, High Surge Current Capability, Reverse Voltage :100 to 1000V,
Forward Current: 0.8A, Designed for Surface Mount Application. HF product.

General purpose.

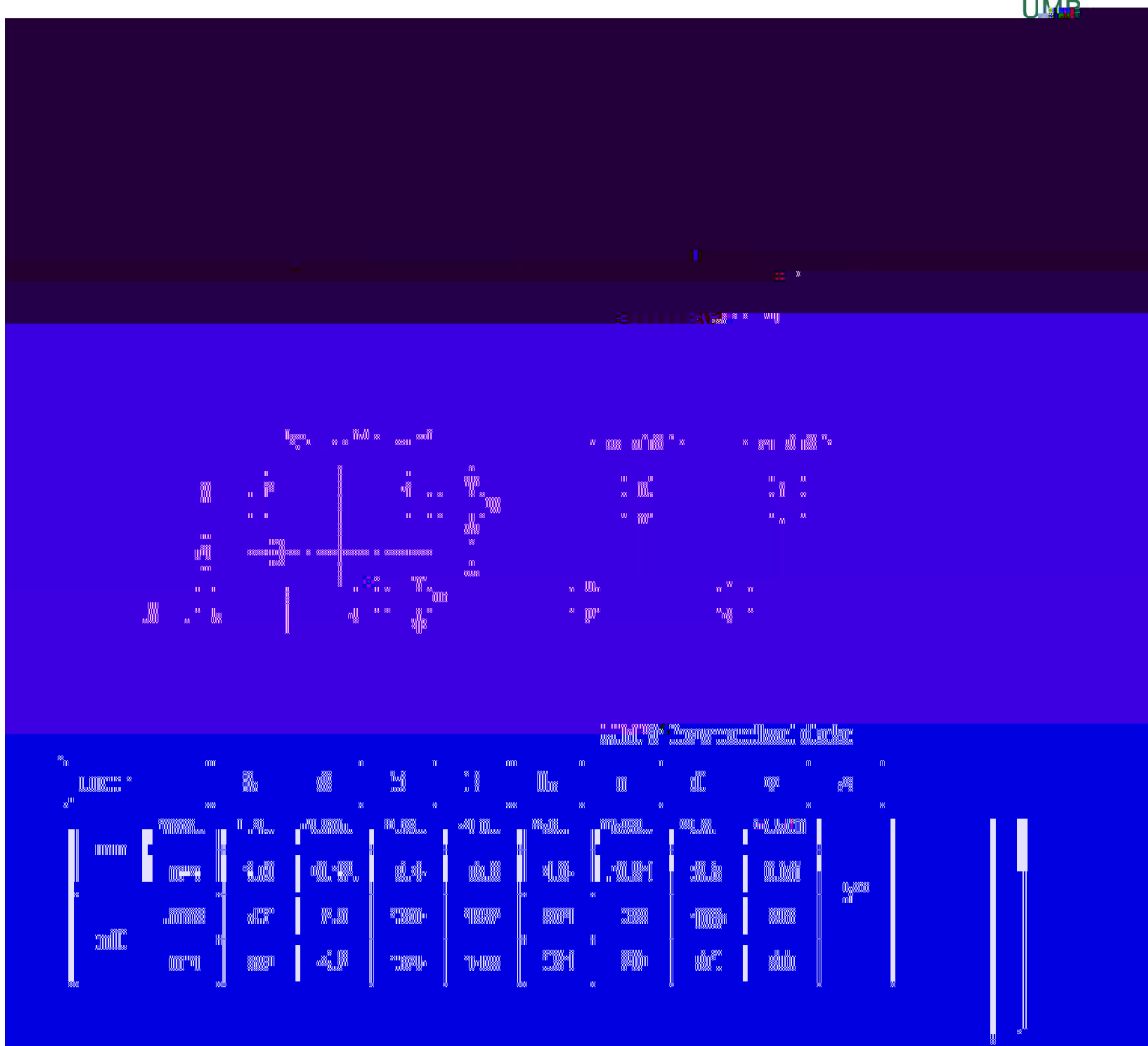
Parameter	Symbol	Rating						Unit
		UM1B	UM2B	UM4B	UM6B	UM8B	UM10B	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_a = 40$	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	25						A
Typical Junction Capacitance Note1	C_i	13						pF
Typical Thermal Resistance Note2	$R_{\theta JA}$	110						/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~150						

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4x1.5 x1.5 (3.81x3.81cm) copper pad areas.

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	$I_F \approx 0.4A$		

/ Package Dimensions



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/ Marking Instructions

UM1B

1 *

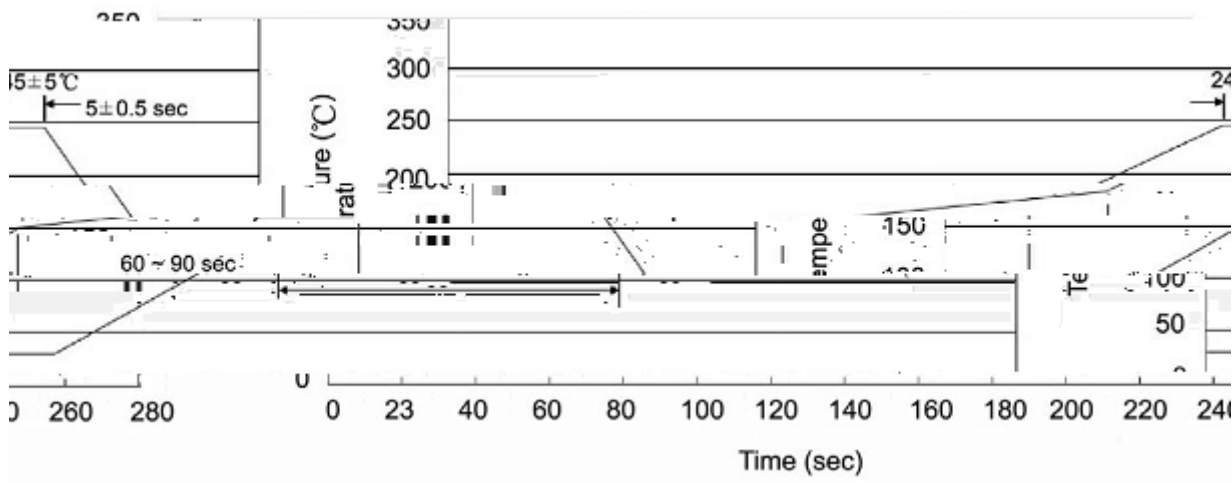
3 *

Note:

UM1B Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 *

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

245±5

5±0.5sec;
- 3

2 10 /sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:245±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box